

Title (en)

A FRACTURE FIXATION DEVICE AND IMPLANTATION JIG THEREFOR

Title (de)

FRAKTURFIXIERUNGSVORRICHTUNG UND IMPLANTIERUNGS AUFSPANNVORRICHTUNG DAFÜR

Title (fr)

DISPOSITIF DE FIXATION DE FRACTURES ET MONTAGE D'IMPLANTATION POUR CELUI-CI

Publication

**EP 1983911 A4 20130220 (EN)**

Application

**EP 06733966 A 20060127**

Priority

US 2006002919 W 20060127

Abstract (en)

[origin: WO2007086854A1] A fracture fixation device includes a plate portion and an intramedullary nail portion which is offset relative to the plate portion by a neck portion. The plate portion includes longitudinally displaced peg holes which orient pegs along an imaginary surface parallel to subchondral bone of an articular surface. The upper surface of the plate portion includes a dimple to reference a jig. The nail portion includes threaded screw holes oriented normal to an endosteal surface, and a smaller K-wire alignment hole parallel to the screw holes. The jig has a first portion which references with the dimple and a second portion in alignment over the screw holes of the nail portion. The back of the first portion of the jig is curved upward to facilitate maneuvering of the jig. The first and second portions of the jig includes K-wire guide holes which direct K-wires relative to holes in the device.

IPC 8 full level

**A61B 17/56** (2006.01); **A61B 17/58** (2006.01); **A61B 17/72** (2006.01); **A61F 2/30** (2006.01); **A61B 17/84** (2006.01)

CPC (source: EP)

**A61B 17/1725** (2013.01); **A61B 17/72** (2013.01); **A61B 17/7233** (2013.01); **A61B 17/8061** (2013.01)

Citation (search report)

- [XY] WO 03101320 A1 20031211 - HAND INNOVATIONS INC [US], et al
- [YA] US 2004193165 A1 20040930 - ORBAY JORGE L [US]
- [E] WO 2006081483 A1 20060803 - DEPUY PRODUCTS INC [US], et al
- [X] US 2002143337 A1 20021003 - ORBAY JORGE L [US], et al
- See references of WO 2007086854A1

Designated contracting state (EPC)

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DOCDB simple family (publication)

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DOCDB simple family (application)

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